

# 2SB1073

## Silicon PNP epitaxial planar type

For low-frequency amplification

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Large peak collector current  $I_{CP}$
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-30	V
Collector-emitter voltage (Base open)	$V_{CEO}$	-20	V
Emitter-base voltage (Collector open)	$V_{EBO}$	-7	V
Collector current	$I_C$	-4	A
Peak collector current	$I_{CP}$	-7	A
Collector power dissipation *	$P_C$	1	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: Print circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

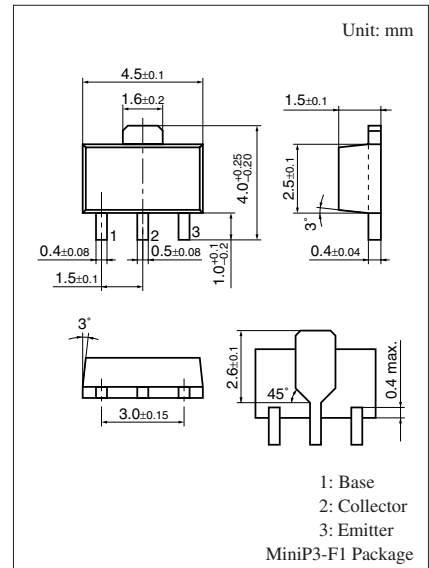
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = -10 \mu\text{A}$ , $I_E = 0$	-30			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -1 \text{ mA}$ , $I_B = 0$	-20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu\text{A}$ , $I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -30 \text{ V}$ , $I_E = 0$			-0.1	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -7 \text{ V}$ , $I_C = 0$			-0.1	$\mu\text{A}$
Forward current transfer ratio *1, 2	$h_{FE}$	$V_{CE} = -2 \text{ V}$ , $I_C = -2 \text{ A}$	120		315	—
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = -3 \text{ A}$ , $I_B = -0.1 \text{ A}$		-0.6	-1.0	V
Transition frequency	$f_T$	$V_{CB} = -6 \text{ V}$ , $I_E = 50 \text{ mA}$ , $f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = -20 \text{ V}$ , $I_E = 0$ , $f = 1 \text{ MHz}$		40		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

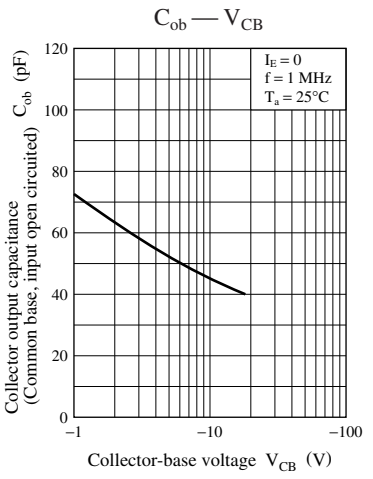
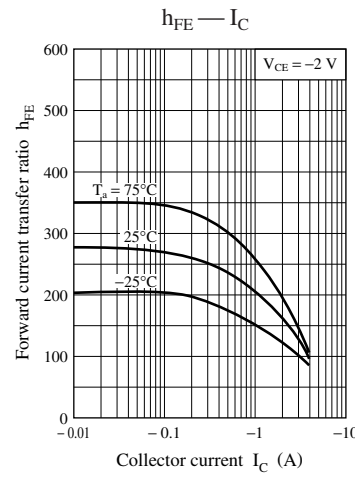
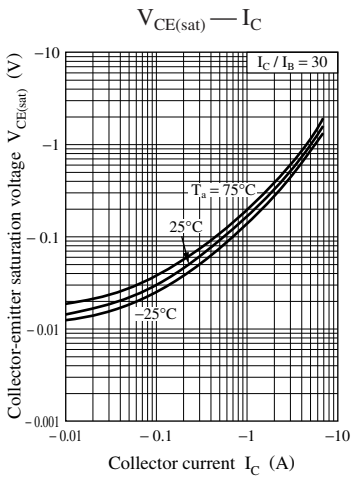
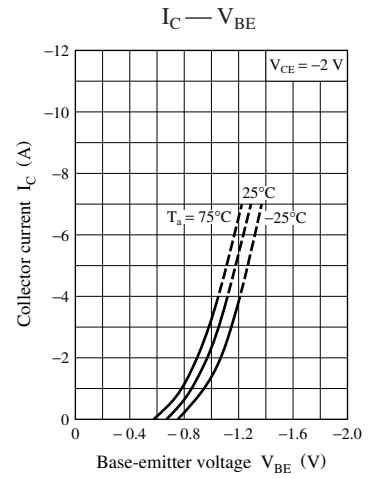
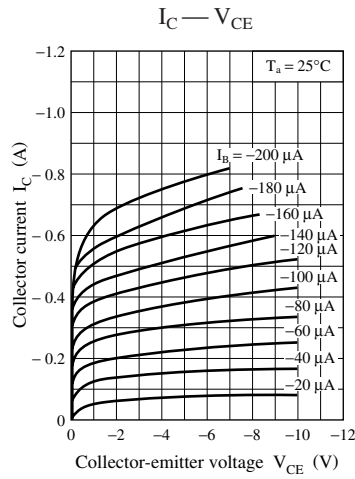
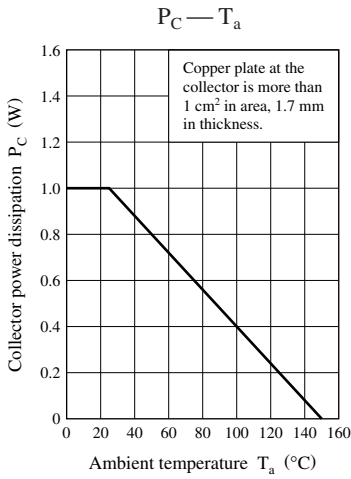
2. \*1: Pulse measurement

\*2: Rank classification

Rank	P	Q
$h_{FE}$	120 to 205	180 to 315



Marking Symbol: I



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